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- ECSEL Research and Innovation Actions (RIA*) –

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– Data generation on OxRAM for Compact model generation –

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Publishable Summary

This report explains and resumes the characterization activity carried out on OxRAM devices with the aim of providing a consistent set of data for compact model calibration. First, it illustrates the test bench, the measurement tools and the Device Under Test (DUT). Next, it resumes the test plan and eventually shows the data results. It is worth noting here that this set of data were obtained on 200mm wafers fabricated in the European projects WakeMeUp and NeuRAM^3, while waiting for 300mm material which is still being processed at the time of writing. We do not expect major differences between the OxRAM devices fabricated in 200 and 300mm wafers. Once the 300mm wafers will be available, a new data set will be produced to update the current set.